UMW SS22F THRU SS220BF

20V-200V 2A

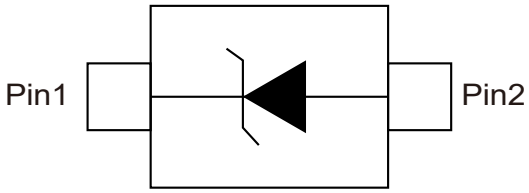
1.Features

- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- Low power loss, high efficiency
- High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications

2.Mechanical Data

- Case: SMBF
- Approx.Weight: 57mg/0.002oz
- Terminals: Solderable per MIL-STD-750 Method 2026

3.Pinning information



SMBF

4.Maximum Ratings And Electrical Characteristics

Parameter		Symbol	SS 22BF	SS 24BF	SS 26BF	SS 28BF	SS 210BF	SS 212BF	SS 215BF	SS 220BF	Units
Maximum Repetitive Peak Reverse Voltage		V_{RRM}	20	40	60	80	100	120	150	200	V
Maximum RMS Voltage		V_{RMS}	14	28	42	56	70	84	105	140	V
Maximum DC Blocking Voltage		V_{DC}	20	40	60	80	100	120	150	200	V
Maximum Average Forward Rectified Current		$I_{F(AV)}$	2								A
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)		I_{FSM}	55				45				A
Max Instantaneous Forward Voltage at 2A		V_F	0.55		0.70		0.85		0.95		V
Maximum DC Reverse Current	T_A=25°C	I_R	0.5			0.3					mA
at Rated DC Reverse Voltage	T_A=100°C		5			3					mA
Typical Junction Capacitance (Note1)		C_J	250			110					pF
Typical Thermal Resistance (Note 2)		$R_{\theta JA}$	65								°C/W
Junction Temperature Range		T_J	-55 to 125								°C
Storage Temperature Range		T_{STG}	-55 to 150								°C

Absolute Maximum Ratings and Electrical characteristics Ratings at ambient temperature unless otherwise specified.Single phase, half wave, 60Hz resistive or inductive load, for capacitive load, derate by 20 %

Notes:

(1) Measured at 1MHz and applied reverse voltage of 4 V D.C.

(2) P.C.B. mounted with 0.5 X 0.5" (12.7X12.7mm) copper pad areas.

5.Typical characteristic

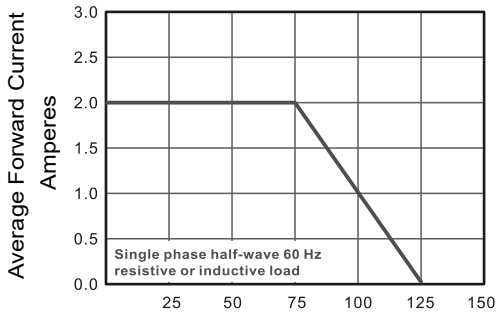


Figure 1: Forward Current Derating Curve

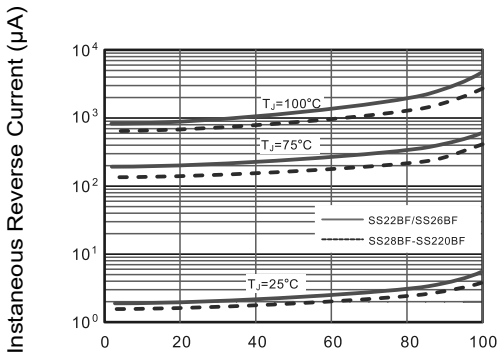


Figure 2: Typical Reverse Characteristics

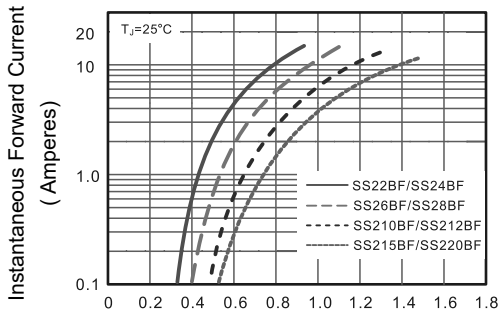


Figure 3: Typical Forward Characteristic

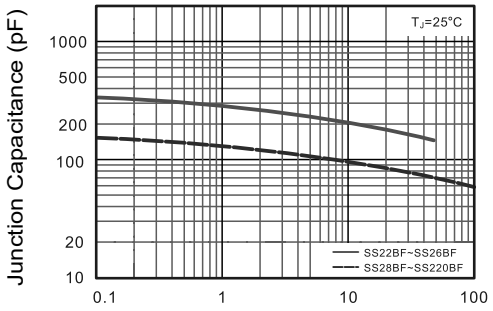


Figure 4: Typical Junction Capacitance

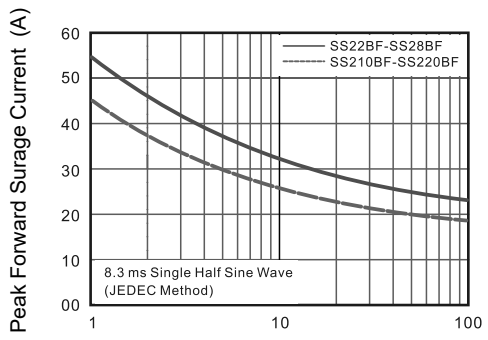


Figure 5: Maximum Non-Repetitive Peak Forward Surage Current

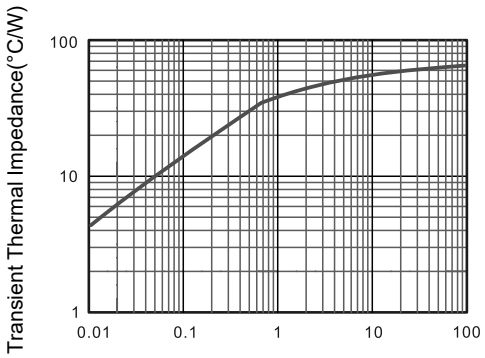
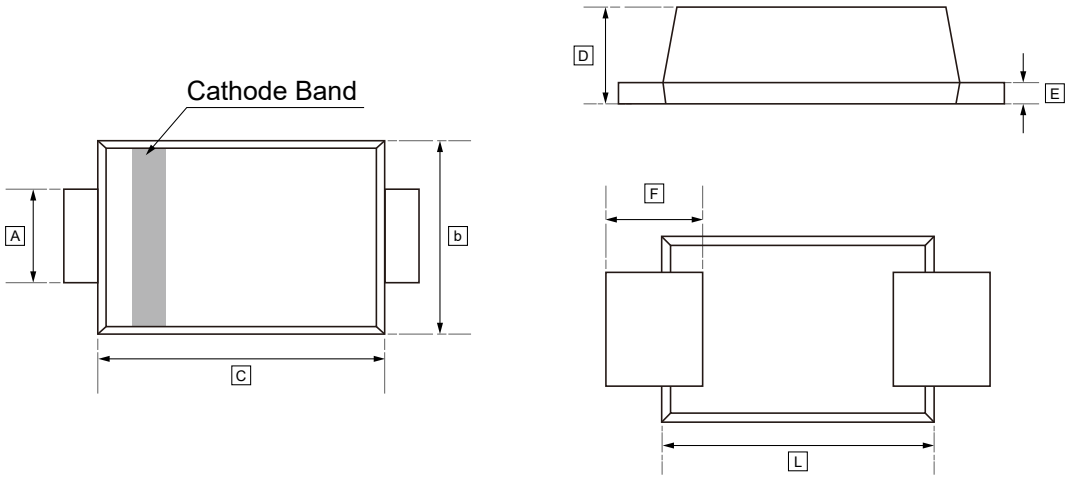


Figure 6: Typical Transient Thermal Impedance

6.SMBF Package Outline Dimensions



DIMENSIONS (mm are the original dimensions)

Symbol	A	b	C	D	E	F	L
Min	1.90	3.50	4.2	1.10	0.18	1.0	5.10
Max	2.20	3.70	4.4	1.30	0.26	1.30	5.5

7 .Ordering information



Order Code	Marking	Package	Base QTY	Delivery Mode
UMW SS22BF	S22B	SMBF	5000	Tape and reel
UMW SS24BF	S24B	SMBF	5000	Tape and reel
UMW SS26BF	S26B	SMBF	5000	Tape and reel
UMW SS28BF	S28B	SMBF	5000	Tape and reel
UMW SS210BF	S210B	SMBF	5000	Tape and reel
UMW SS212BF	S212B	SMBF	5000	Tape and reel
UMW SS215BF	S215B	SMBF	5000	Tape and reel
UMW SS220BF	S220B	SMBF	5000	Tape and reel

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